TECHNOLOGY NEWS

NXP demonstrates new car-to-x communication platform: major milestone towards safer road traffic

Eindhoven, Netherlands, May 16, 2011 – NXP Semiconductors N.V. (Nasdaq: NXPI) today gave a live demonstration of car-to-x (C2X) communication on a public road in the Netherlands. With this demo NXP is the first semiconductors company that took the step from showing concepts to actually demonstrating an automotive-ready hardware platform for connected mobility. NXP has co-developed the C2X platform with Australian-based Cohda Wireless. Combined with telematics for location-based services and networking security, the platform enables the fully connected car and is therefore a major milestone towards mass deployment for safer road traffic.

C2X communication uses IEEE802.11p, a wireless standard designed specifically for automotive applications. This allows cars to communicate with each other (car-to-car) as well as with intelligent traffic infrastructure (car-to-infrastructure) around them. The newly developed C2X platform from NXP and Cohda actually "sees" around corners in order to recognize traffic blocks or risks before they are visible by the human eye. Drivers therefore receive early warnings of cars hidden from sight behind trucks or approaching from around corners. Other use cases are warnings of emergency vehicles and traffic jams, or traffic light signals allowing drivers to adjust their speed and optimize their driving.

The C2X platform is able to meet the requirements of the automotive industry: reliable signal reception for fast moving objects even in difficult surroundings, cost-efficient design, and flexible programming." It uses Cohda's Advanced IEEE 802.11p radio and is based on NXP's multi-standard radio reception platform. NXP's expertise as global leader in car entertainment semiconductors and Cohda's patented reception algorithms are critical factors for the successful development.

The C2X demo is one of several connected mobility demos which NXP presents during Automotive Week 2011, from 14 to 22 May 2011 in Eindhoven, the Netherlands. As project leader of the Dutch SPITS research project (SPITS: Strategic Platform for Intelligent Transport Systems) NXP is a major contributor to the Automotive Week. For a whole week the Brainport Region is the international stage for the latest technological developments in the automotive field. Industry, Dutch government and research institutes are joining forces with the theme of 'Building the Future in Mobility'. Other demonstrations from NXP at Automotive Week 2011 include intelligent traffic data analysis from the in-vehicle networks, as well as emergency and breakdown calls based on NXP’s telematics module, ATOP.
Kurt Sievers, Senior Vice President and General Manager of the Automotive business at NXP Semiconductors explains: “Connecting the car to the environment demands in-depth expertise in secure connectivity, Software-Defined Radio architectures, and telematics. These technologies are at the very heart of NXP’s automotive portfolio. NXP has therefore set high priority on gaining the pole position in connected mobility. The SPITS project has been extremely valuable for us as it brought experts and research partners from all parts of the value chain together who are all working towards the same goal: efficient and sustainable mobility solutions.”

For more information, please visit:
www.nxp.com/spits
www.automotiveweek.nl

About SPITS project

SPITS stands for Strategic Platform for Intelligent Transport Systems. SPITS is about ensuring that mobility become more efficient and sustainable. It focuses on three main areas: traffic management and safety, concepts for open in-car platform, and downloadable services. SPITS was aimed at creating an open and affordable intelligent transport system platform, which is scalable, secure and real-time. The Dutch Ministry of Economic Affairs has subsidised the project. The consortium is lead by NXP Semiconductors and consists of eight companies (NXP, TomTom, TNO, Logica, Catena, Task24, Foutress, GreenCat), one research institute, and four universities. These partners cover the entire mobility value chain, enabling the complete development of all elements necessary in the system. The SPITS project has involved two years of innovative thinking, close cooperation between organisations, and the construction of prototypes to prove the validity of the system. The SPITS system comprises the vehicle on-board unit (OBU), the Road Side Unit (RSU) infrastructure, and the Back Office (BO) service centre. Communications between these elements is a major part of the Strategic Platform. After the SPITS project officially ends, consortium members will continue to refine the SPITS results for commercial use across Europe and beyond. These projects represent an investment by the Government to retain key knowledge from R&D companies within the Netherlands, following the economic crisis.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications. A global semiconductor company with operations in more than 30 countries, NXP posted revenue of $4.4 billion in 2010. For more information, visit www.nxp.com.
Forward-looking Statements

This document includes forward-looking statements which include statements regarding our business strategy, financial condition, results of operations, and market data, as well as any other statements which are not historical facts. By their nature, forward-looking statements are subject to numerous factors, risks and uncertainties that could cause actual outcomes and results to be materially different from those projected. These factors, risks and uncertainties include the following: market demand and semiconductor industry conditions, our ability to successfully introduce new technologies and products, the demand for the goods into which our products are incorporated, our ability to generate sufficient cash, raise sufficient capital or refinance our debt at or before maturity to meet both our debt service and research and development and capital investment requirements, our ability to accurately estimate demand and match our production capacity accordingly or obtain supplies from third-party producers, our access to production from third-party outsourcing partners, and any events that might affect their business or our relationship with them, our ability to secure adequate and timely supply of equipment and materials from suppliers, our ability to avoid operational problems and product defects and, if such issues were to arise, to rectify them quickly, our ability to form strategic partnerships and joint ventures and successfully cooperate with our alliance partners, our ability to win competitive bid selection processes to develop products for use in our customers’ equipment and products, our ability to successfully establish a brand identity, our ability to successfully hire and retain key management and senior product architects; and, our ability to maintain good relationships with our suppliers. In addition, this document contains information concerning the semiconductor industry and our business segments generally, which is forward-looking in nature and is based on a variety of assumptions regarding the ways in which the semiconductor industry, our market segments and product areas will develop. We have based these assumptions on information currently available to us, if any one or more of these assumptions turn out to be incorrect, actual market results may differ from those predicted. While we do not know what impact any such differences may have on our business, if there are such differences, our future results of operations and financial condition, and the market price of the notes, could be materially adversely affected. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak to results only as of the date the statements were made; and, except for any ongoing obligation to disclose material information as required by the United States federal securities laws, we do not have any intention or obligation to publicly update or revise any forward-looking statements after we distribute this document, whether to reflect any future events or circumstances or otherwise. For a discussion of potential risks and uncertainties, please refer to the risk factors listed in our SEC filings. Copies of our filings are available from our Investor Relations department or from the SEC website, www.sec.gov.

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